Package Outline Dimension

NOTES:
2. CONTROLLING DIMENSIONS: MILLIMETER. CONVERTED INCH
   DIMENSION ARE NOT NECESSARILY EXACT.
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS
   MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. INSULATION THICKNESS, CLEARANCE OF OVERLAP ARE USER DEFINED.
5. INSULATION NOT COMPLETELY SHOWN FOR REASONS OF CLARITY.
1.8-2.7 GHz 2W High Linearity 5V 2-Stage Power Amplifier

Suggested PCB Land Pattern and PAD Layout

- Notes
  1. Use 1 oz. copper minimum for top and bottom layer metal.
  2. A heatsink underneath the area of the PCB for the mounted device is required for proper thermal operation.
  3. Ground / thermal vias are critical for the proper performance of this device.
     Vias should use a 0.5 mm(A) diameter drill and have a final plated thru diameter of 0.3 mm(B).

Package Marking

YY = Year, WW = Working Week,
XX = Wafer No.